

NCE P-Channel Enhancement Mode Power MOSFET

Description

The NCE01P30K uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications. It is ESD protested.

General Features

● V_{DS} =-100V,I_D =-30A

 $R_{DS(ON)}$ <45m Ω @ V_{GS} =-10V (Typ:39m Ω)

 $R_{DS(ON)}$ <50m Ω @ V_{GS} =-4.5V (Typ:42m Ω)

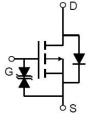
- Super high dense cell design
- Advanced trench process technology
- Reliable and rugged
- High density cell design for ultra low On-Resistance

Application

Portable equipment and battery powered systems

100% UIS TESTED!

100% ΔVds TESTED!



Schematic diagram



Marking and pin assignment



TO-252-2L top view

Package Marking and Ordering Information

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Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE01P30K	NCE01P30K	TO-252-2L	-	_	-

Absolute Maximum Ratings (T_c=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	-100	V	
Gate-Source Voltage	V _G s	±20	V	
Drain Current-Continuous	I _D	-30	А	
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	-21	Α	
Pulsed Drain Current	I _{DM}	-150	Α	
Maximum Power Dissipation	P _D	91	W	
Single pulse avalanche energy (Note 5)	E _{AS}	420	mJ	
Derating factor		0.6	W/°C	
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 175	°C	

Thermal Characteristic

Thermal Resistance,Junction-to-Case (Note 2)	R _{θJc}	1.65	°C/W
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Electrical Characteristics (T_C=25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	<u>'</u>		'			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250µA	-100	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-100V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±10	μA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =-250μA	-1.5	-1.8	-2.5	V
Dunin Course On Chata Besintance	R _{DS(ON)}	V _{GS} =-10V, I _D =-15A	-	39	45	mΩ
Drain-Source On-State Resistance		V _{GS} =-4.5V, I _D =-15A	-	42	50	mΩ
Forward Transconductance	g FS	V _{DS} =-20V,I _D =-10A	-	42	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss})/ F0/// 0//	-	6978	-	PF
Output Capacitance	Coss	V_{DS} =-50V, V_{GS} =0V, F=1.0MHz	-	200.8	-	PF
Reverse Transfer Capacitance	C _{rss}	F-1.UIVIDZ	-	194.8	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	17	-	nS
Turn-on Rise Time	t _r	V_{DD} =-50V, I_{D} =-15A V_{GS} =-10V, R_{GEN} =9.1 Ω	-	80	-	nS
Turn-Off Delay Time	t _{d(off)}		-	45	-	nS
Turn-Off Fall Time	t _f		-	65	-	nS
Total Gate Charge	Qg		-	128	-	nC
Gate-Source Charge	Qgs	V _{DS} =-50V,I _D =-15A, V _{GS} =-10V	-	17.9	-	nC
Gate-Drain Charge	Q _{gd}	V _{GS} =-10V	-	25.6	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =-15A	-	-	-1.2	V
Diode Forward Current (Note 2)	Is	-	-	-	-30	Α
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF =-15A	-	90	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3)	-	150	-	nC
Forward Turn-On Time	ton	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				y LS+LD)

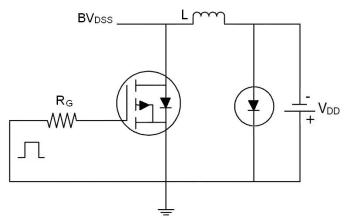
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production

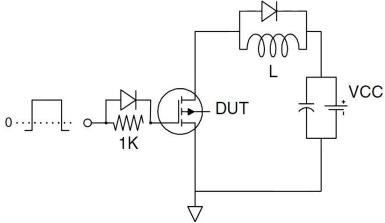


Test Circuit

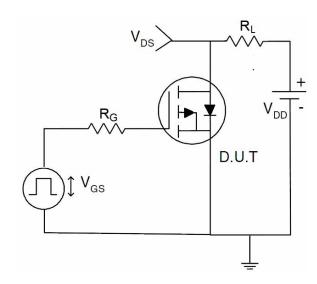
1) Eas Test Circuit



2) Gate Charge Test Circuit



3) Switch Time Test Circuit





Typical Electrical and Thermal Characteristics (Curves)

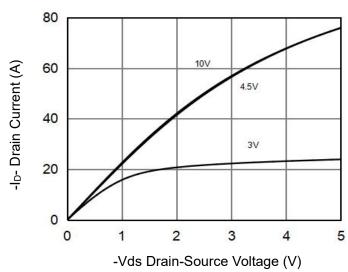


Figure 1 Output Characteristics

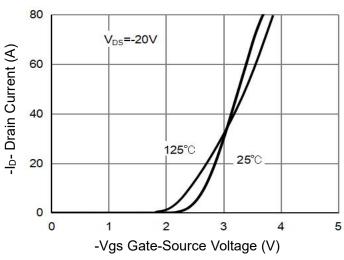


Figure 2 Transfer Characteristics

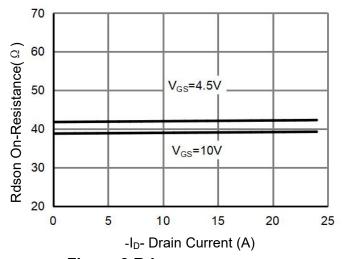


Figure 3 Rdson- Drain Current

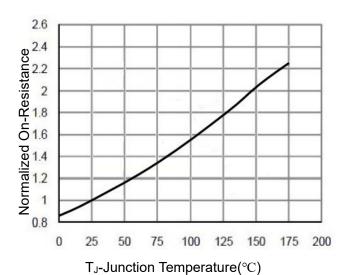


Figure 4 Rdson-JunctionTemperature

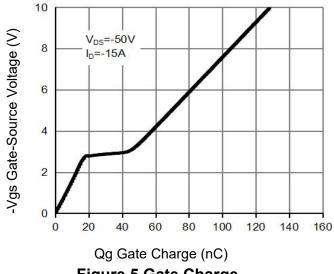


Figure 5 Gate Charge

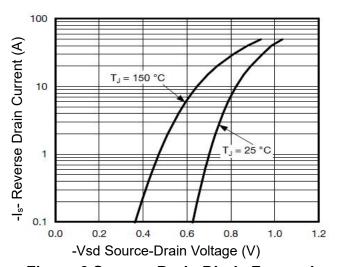


Figure 6 Source- Drain Diode Forward



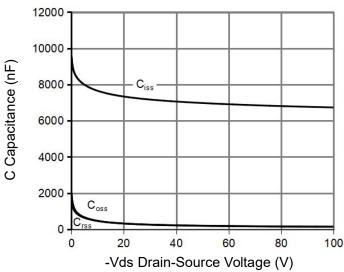


Figure 7 Capacitance vs Vds

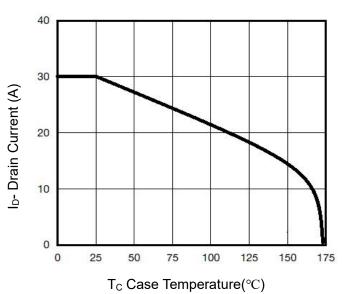


Figure 9 Drain Current vs Case Temperature

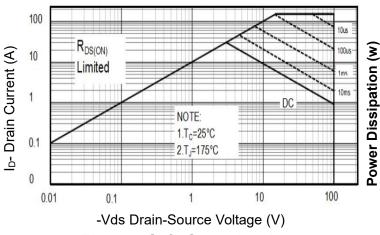


Figure 8 Safe Operation Area

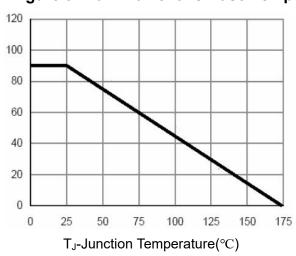


Figure 10 Power De-rating

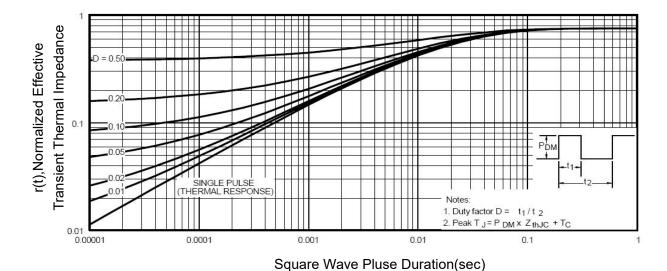
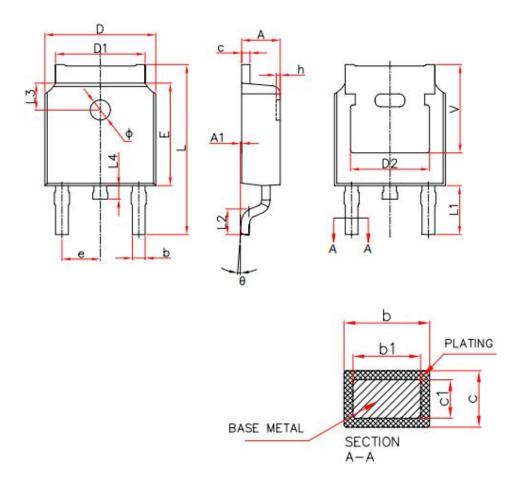


Figure 11 Normalized Maximum Transient Thermal Impedance



TO-252 Package Information



Cumbal	Millimeters		
Symbol	Min.	Max.	
Α	2.20	2.40	
A1	0.00	0.13	
b	0.66	0.86	
b1	0.73	0.79	
С	0.46	0.58	
c1	0.50	0.52	
D	6.50	6.70	
D1	5.10	5.46	
D2	4.83 REF.		
E	6.00	6.20	
е	2.19	2.39	
L	9.80	10.40	
L1	2.90 REF.		
L2	1.40	1.70	
L3	1.60 REF.		
L4	0.60	1.00	
Ф	1.10	1.30	
θ	0°	8°	
h	0.00	0.30	
V	5.35 REF.		

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